



FLINT HILLS SOLUTIONS

TRANSFORMING IDEAS INTO REALITY...

MINIATURIZATION DESIGN and SMT ASSEMBLY

KEY CAPABILITIES

REQUIREMENTS

- Systems
- Components BOM
- Environmental
- FAA

DESIGN

- STANDARD MINIATURIZATION**
 -Design for standard off the shelf miniaturized components
- ULTRA MINIATURIZATION**
 -Design for new miniaturized Components including System in Package, Die Stacking and Flip Chip

SMT RAPID PROTOTYPING

- Class 10,000 (clean room)
- Epoxy and Eutectic Die Attach
- Dam and Under Fill, Dispensed Encapsulation (Glob-Top)
- Transfer Mold Encapsulation
- Stencil Screen Printing
- Fine Pitch Pick and Place
- Reflow (N2 environment)
- IPC Standards
- No-Lead and RoHs Compliant Capable

PACKAGING

- Box Level Thermal Design
- I/O
- Power
- Environmental Qualifications

Electronic Miniaturization Specializing in Unmanned Systems

PAYLOADS

AUTOPILOTS

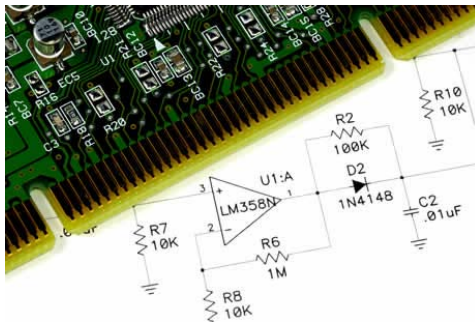
NAVIGATION

CAMERAS

SENSORS

FLINT HILLS SOLUTIONS' *Advanced Avionics Miniaturization Program* is dedicated to the miniaturization and advanced electronics technology insertion into Unmanned Air Systems including payloads (EO/IR Cameras, Sensors, etc) and Autopilot/Navigation systems.

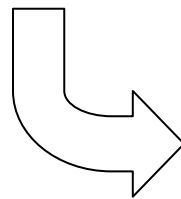
FHS Miniaturization Process



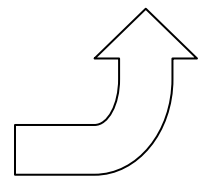
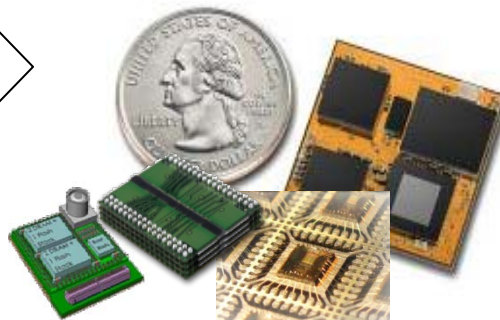
DESIGN



UAS INTEGRATION



MINIATURIZATION



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